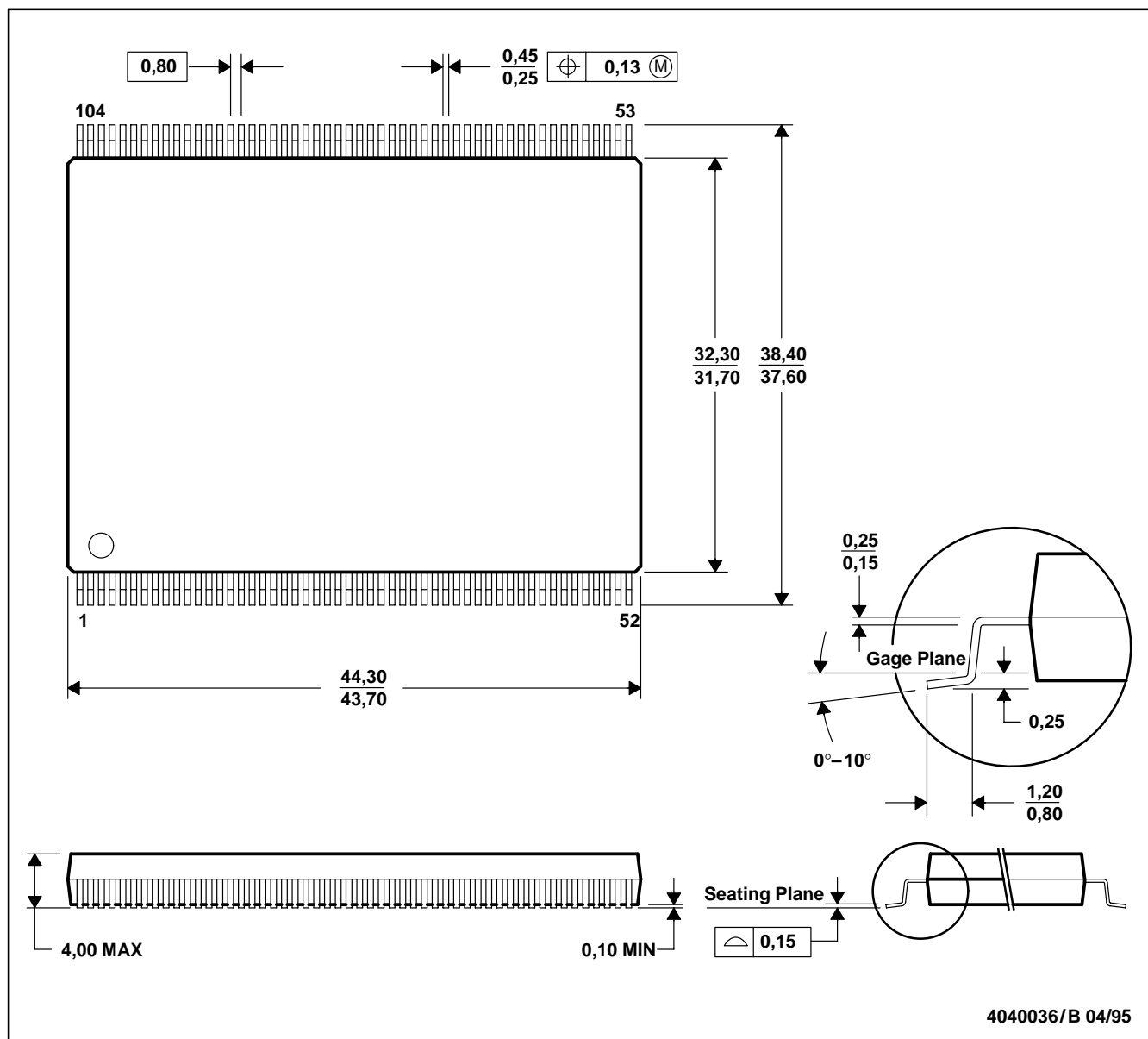


PA (R-PDSO-G104)

PLASTIC DUAL SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. This package is designed for a ceramic MCM substrate to be mounted on the lead frame pad and wire bonded to the lead fingers.

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